

Requested Patent: JP4056262
Title: SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE
Abstracted Patent: JP4056262
Publication Date: 1992-02-24
Inventor(s): SANAI SUSUMU
Applicant(s): MATSUSHITA ELECTRON CORP
Application Number: JP19900167207 19900625
Priority Number(s):
IPC Classification: H01L25/065 ; H01L25/07 ; H01L25/18 ; H01L27/00
Equivalents:

ABSTRACT:

PURPOSE: To enable a semiconductor integrated circuit device to be miniaturized and improved in electrical properties by a method wherein two or more semiconductor chips are stacked up on a board.

CONSTITUTION: Semiconductor chips 1, 2, and 3 are stacked up on a thin Au film 10 on a board 4 and bonded, and the chips 1, 2, and 3 are connected to a wiring 6 provided onto the board 4 with bonding wires, and the chips are coated hard with resin 7 except a bonding part on the board. Then, the chip 2 is bonded with an adhesive agent 8, the chip 2 is connected to the wiring 6 provided onto the board 4 through bonding, and a process the same as above is repeated, whereby the chip 3 is connected to the wiring 6 on the board 4. Lastly, the whole body is covered with a resin 9.